



Embedded Vision Alliance awards REAL3 image sensor as “Product of the Year”

Munich, Germany – 23 May 2019 – Smartphone cameras increasingly require 3D vision capabilities as differentiating factor. Hence, Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) and pmdtechnologies ag jointly developed the REAL3™ IRS2381C, a premier 3D imager sensor solution especially designed for the mobile device market. The Embedded Vision Alliance now awarded the 3D Time-of-Flight (ToF) single chip solution as “Product of the Year” in the category “Sensors”. The Award recognizes the innovation and achievement of the industry’s leading technologies, services, and products from companies enabling next generation of practical applications for computer vision.

“Congratulations to Infineon for winning Best Sensor in our 2019 Vision Product of the Year awards,” said Jeff Bier, Founder of the Embedded Vision Alliance.

“Innovative sensor designs, like Infineon's 3D Image Sensor, are enabling new 3D vision experiences such as smartphone face recognition and augmented reality. Infineon has been a pioneer in creating 3D image sensors for visual AI applications. I applaud the company’s ongoing investment in innovation and quality in this rapidly changing and often confusing market. I’m proud that Infineon is a member of the Embedded Vision Alliance and delighted they have been recognized with this outstanding honor.”

“We would like to thank the Embedded Vision Alliance for having honored us with the ‘Product of the Year’ Award, which recognizes Infineon’s innovation and performance of our REAL3™ ToF-based 3D imager the category ‘Sensors’, said Philipp von Schierstaedt, Vice President, RF & Sensors, Infineon. “Building upon the combined expertise of Infineon and pmdtechnologies, the novel sensor delivers a new level of 3D camera capabilities in mobile device applications. Infineon’s REAL3™ ToF sensor enables a unique user’s experience in secure face-authentication, computational photography and seamless AR-applications”.



Time-of-Flight (ToF) is the most advanced image sensing technology powering 3D cameras in new generation mobile devices and is posed to fuel the dramatic growth of 3D image sensing application market expected for future years. “Time-of-flight” stands for the time the photons need to travel from the camera to the subject or object of desire and back to the REAL3 sensor. Behind this concept there is unparalleled innovation: it enables the next level of highly secure user smartphone interaction.

The awarded IRS2381C image sensor ensures a high-quality, real time and secure 3D vision experience with supreme performance at all light conditions including outdoor. Compared to other 3D technologies like structured light, Infineon’s and pmd’s 3D ToF technology reduces the number of key components from three to two. Moreover, as distance is measured directly, it requires the least computational resources on the application processor. All this makes the application much more reliable, reduces the size and leads to more competitive costs, while enormously cutting the power drain.

Availability

The new 3D image sensor chip was developed in Graz, Dresden and Siegen and combines the know-how of these locations in a single solution. With proven high volume production and a fast, in-factory enabled and lifetime valid calibration process, IRS2381C is the 3D image sensor of choice for 3D camera manufacturing in mobile device applications. More information about Infineon's 3D image sensor family is available at www.infineon.com/real3.

About Infineon

Infineon Technologies AG is a world leader in semiconductor solutions that make life easier, safer and greener. Microelectronics from Infineon is the key to a better future. In the 2018 fiscal year (ending 30 September), the Company reported sales of €7.6 billion with about 40,100 employees worldwide. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNNY).

Further information about REAL3™ is available at www.infineon.com/real3

About pmdtechnologies

pmdtechnologies ag, a fabless IC company headquartered in Siegen/Germany with subsidiaries in the USA, China and Korea, is the worldwide leading 3D Time-of-Flight CMOS-based digital imaging technology supplier. Started up in 2002, the company owns over 350 worldwide patents concerning pmd-based applications, the pmd measurement principle and its realization. Addressed markets for pmd's 3D sensors are industrial automation, automotive and the wide field of consumer applications like smartphones. Further information is available at pmdtec.com.

pmdtechnologies ag | contact

Sabrina Buxbaum
Director Corporate Strategy & Marketing
Phone: +49 271 238 712 800
E-Mail: s.buxbaum@pmdtec.com

Infineon Technologies AG | contact

Gregor Rodehueser
Press Spokesperson
Markets & Business Development
Phone: +49 89 234 28 481
E-Mail: gregor.rodehueser@infineon.com